# 阅读申明

- 1.本站收集的数据手册和产品资料都来自互联网,版权归原作者所有。如读者和版权方有任何异议请及时告之,我们将妥善解决。
- 2.本站提供的中文数据手册是英文数据手册的中文翻译,其目的是协助用户阅读,该译文无法自动跟随原稿更新,同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。
- 3.本站提供的产品资料,来自厂商的技术支持或者使用者的心得体会等,其内容可能存在描 叙上的差异,建议读者做出适当判断。
- 4.如需与我们联系,请发邮件到marketing@iczoom.com,主题请标有"数据手册"字样。

# **Read Statement**

- 1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.
- 2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader's learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.
- 3. All product information provided on the website refer to solutions from manufacturers' technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.
- 4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with "Datasheets" .



### GaN on SiC HEMT Pulsed Power Transistor 45 W Peak, DC-3500 MHz, 1 ms Pulse, 10% Duty

Rev. V2

#### **Features**

- GaN on SiC Depletion Mode Transistor
- Common-Source Configuration
- Broadband Class AB Operation
- Thermally Enhanced Cu/Mo/Cu Package
- RoHS\* Compliant
- +50V Typical Operation
- MTTF = 600 years (T<sub>J</sub> < 200°C)</li>

#### **Application**

· Civilian and Military Pulsed Radar

#### **Description**

The MAGX-000035-045000 is a gold metalized unmatched Gallium Nitride (GaN) on Silicon Carbide (SiC) RF power transistor optimized for civilian and military radar pulsed applications between DC - 3500 MHz. Using state of the art wafer fabrication processes, these high performance transistors provide high gain, efficiency, bandwidth and ruggedness over a wide bandwidth for today's demanding application needs. The MAGX-000035-045000 is constructed using a thermally enhanced Cu/Mo/Cu flanged ceramic package which provides excellent thermal performance. High breakdown voltages allow for reliable and stable operation in extreme mismatched load conditions unparalleled with older semiconductor technologies.

#### MAGX-000035-045000



#### **Ordering Information**

Part Number	Description
MAGX-000035-045000	Bulk Packaging
MAGX-S10035-045000	Sample Board (2.7 - 3.5 GHz)

<sup>\*</sup> Restrictions on Hazardous Substances, European Union Directive 2002/95/EC.



### GaN on SiC HEMT Pulsed Power Transistor 45 W Peak, DC-3500 MHz, 1 ms Pulse, 10% Duty

Rev. V2

## Electrical Specifications<sup>1</sup>: Freq. = 2700-3500 MHz, T<sub>A</sub> = 25°C

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
RF Functional Tests: $V_{DD} = 50 \text{ V}$ , $I_{C}$	RF Functional Tests: V <sub>DD</sub> = 50 V, I <sub>DQ</sub> = 100 mA, 1 ms Pulse, 10% Duty					
Output Power	P <sub>IN</sub> = 4 W	P <sub>OUT</sub>	45	54	-	W
Power Gain	P <sub>IN</sub> = 4 W	G <sub>P</sub>	10.5	11.3	-	dB
Drain Efficiency	P <sub>IN</sub> = 4 W	$\eta_{D}$	48	55	-	%
Input Return Loss	P <sub>IN</sub> = 4 W	IRL	-	-8	-	dB
Load Mismatch Stability	P <sub>IN</sub> = 4 W	VSWR-S	-	5:1	-	-
Load Mismatch Tolerance	P <sub>IN</sub> = 4 W	VSWR-T	-	10:1	-	-

## Electrical Specifications<sup>1</sup>: Freq. = 1030-1090 MHz, T<sub>A</sub> = 25°C

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
RF Functional Tests: V <sub>DD</sub> = 50 V, I <sub>DQ</sub> = 100 mA, 1 ms Pulse, 10% Duty						
Output Power	P <sub>IN</sub> = 0.9 W	P <sub>OUT</sub>	-	60	-	W
Power Gain	P <sub>IN</sub> = 0.9 W	G <sub>P</sub>	-	18	-	dB
Drain Efficiency	P <sub>IN</sub> = 0.9 W	$\eta_{D}$	-	64	-	%
Input Return Loss	P <sub>IN</sub> = 0.9 W	IRL	-	-8	-	dB
Load Mismatch Stability	P <sub>IN</sub> = 0.9 W	VSWR-S	-	5:1	-	-
Load Mismatch Tolerance	P <sub>IN</sub> = 0.9 W	VSWR-T	-	10:1	-	-

### Electrical Characteristics: $T_A = 25$ °C

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
DC Characteristics	DC Characteristics					
Drain-Source Leakage Current	V <sub>GS</sub> = -8 V, V <sub>DS</sub> = 175 V	I <sub>DS</sub>	-	-	3.0	mA
Gate Threshold Voltage	$V_{DS} = 5 \text{ V}, I_{D} = 6 \text{ mA}$	V <sub>GS (TH)</sub>	-5	-3	-2	V
Forward Transconductance	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 1500 mA	G <sub>M</sub>	1.1	-	-	S
Dynamic Characteristics						
Input Capacitance	$V_{DS} = 0 \text{ V}, V_{GS} = -8 \text{ V}, F = 1 \text{ MHz}$	C <sub>ISS</sub>	-	13.2	-	pF
Output Capacitance	$V_{DS} = 50 \text{ V}, \ V_{GS} = -8 \text{ V}, \ F = 1 \text{ MHz}$	Coss	-	5.6	-	pF
Reverse Transfer Capacitance	$V_{DS} = 50 \text{ V}, \ V_{GS} = -8 \text{ V}, \ F = 1 \text{ MHz}$	C <sub>RSS</sub>	-	0.5	-	pF



### **GaN on SiC HEMT Pulsed Power Transistor** 45 W Peak, DC-3500 MHz, 1 ms Pulse, 10% Duty

Rev. V2

### **Absolute Maximum Ratings**<sup>2,3,4</sup>

Parameter	Limit
Supply Voltage (V <sub>DD</sub> ) (Pulsed)	+65 V
Supply Voltage (V <sub>Gg</sub> )	-8 to 0 V
Supply Current ( $I_{DMAX}$ ) for pulsed operation at $V_{DD}$ = 50 V	3 A
Input Power ( $P_{IN}$ ) for pulsed operation at $V_{DD}$ = 50 V	P <sub>IN</sub> (nominal) + 3 dB
Absolute Max. Junction/Channel Temperature	200°C
Power Dissipation at 85 °C for pulsed operation at V <sub>DD</sub> = 50 V	48 W
MTTF (T <sub>J</sub> <200°C)	600 years
Thermal Resistance, ( $T_J$ = 200 °C) $V_{DD}$ = 50 V, $I_{DQ}$ = 100 mA, Pulsed 1 ms, 10% Duty Cycle	2.3 °C/W
Operating Temperature	-40 to +95°C
Storage Temperature	-65 to +150°C
Mounting Temperature	See solder reflow profile
ESD Min Charged Device Model (CDM)	200 V
ESD Min Human Body Model (HBM)	550 V

Operation of this device above any one of these parameters may cause permanent damage.
 Channel temperature directly affects a device's MTTF. Channel temperature should be kept as low as possible to maximize lifetime.

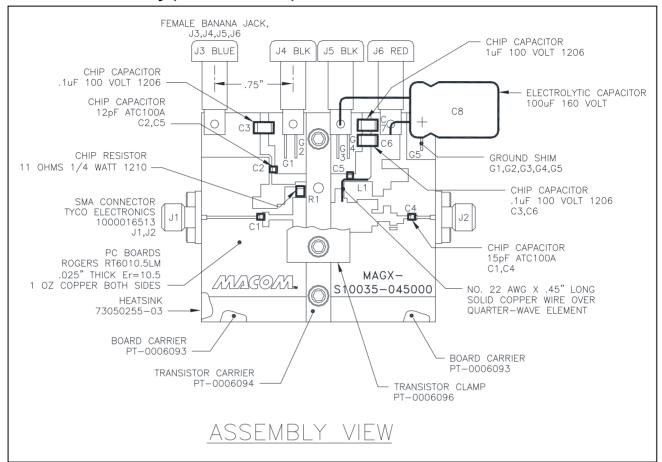
<sup>4.</sup> For saturated performance it is recommended that the sum of (3\*V<sub>DD</sub> + abs(V<sub>GG</sub>)) <175 V.



GaN on SiC HEMT Pulsed Power Transistor 45 W Peak, DC-3500 MHz, 1 ms Pulse, 10% Duty

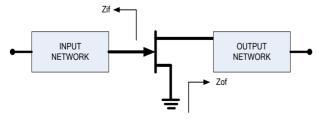
Rev. V2

#### Test Fixture Assembly (2700-3500 MHz)



#### **Test Fixture Impedances**

F (MHz)	Z <sub>IF</sub> (Ω)	Z <sub>OF</sub> (Ω)
2700	7.7 - j3.9	7.5 + j3.0
2900	8.0 - j5.2	7.9 + j1.8
3100	7.2 - j6.8	7.5 + j8.3
3300	5.2 - j7.7	6.8 + j3.9
3500	3.1 - j7.1	6.0 + j7.1



#### **Correct Device Sequencing**

#### Turning the device ON

- 1. Set  $V_{GS}$  to the pinch-off  $(V_P)$ , typically -5 V.
- 2. Turn on V<sub>DS</sub> to nominal voltage (+50V).
- 3. Increase V<sub>GS</sub> until the I<sub>DS</sub> current is reached.
- 4. Apply RF power to desired level.

#### **Turning the device OFF**

- 1. Turn the RF power off.
- 2. Decrease  $V_{\text{GS}}$  down to  $V_{\text{P}}$
- 3. Decrease V<sub>DS</sub> down to 0 V.
- 4. Turn off V<sub>GS</sub>

M/A-COM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.

Visit <a href="https://www.macom.com">www.macom.com</a> for additional data sheets and product information.

Contact factory for Gerber file or additional circuit information.



GaN on SiC HEMT Pulsed Power Transistor 45 W Peak, DC-3500 MHz, 1 ms Pulse, 10% Duty

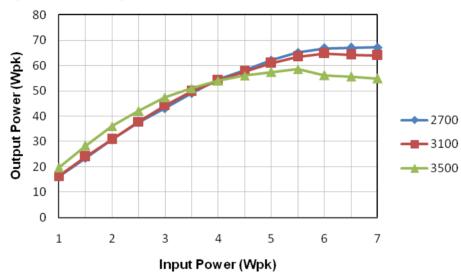
Rev. V2

### **Application Section**

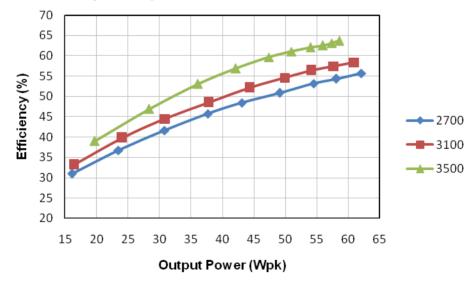
#### **Typical Performance Curves**

2700 - 3500 MHz, 1 ms Pulse, 10% Duty,  $V_{DD}$  = 50 V, Idq = 100 mA,  $T_A$  = 25°C

#### **Output Power Vs. Input Power**



#### Drain Efficiency Vs. Output Power





GaN on SiC HEMT Pulsed Power Transistor 45 W Peak, DC-3500 MHz, 1 ms Pulse, 10% Duty

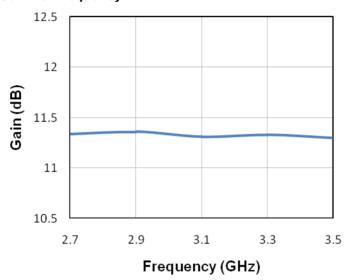
Rev. V2

## **Application Section**

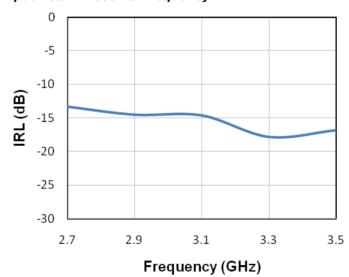
#### **Typical Performance Curves**

2700 - 3500 MHz, 1 ms Pulse, 10% Duty,  $V_{DD}$  = 50 V, Idq = 100 mA,  $T_A$  = 25°C

#### Gain vs. Frequency



#### Input Return Loss vs. Frequency





GaN on SiC HEMT Pulsed Power Transistor 45 W Peak, DC-3500 MHz, 1 ms Pulse, 10% Duty

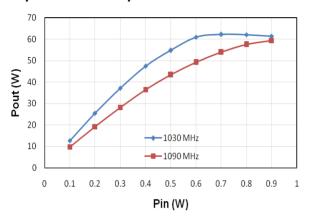
Rev. V2

## **Application Section**

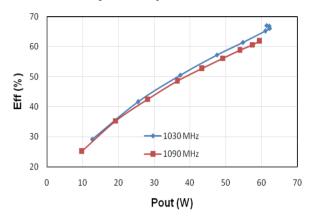
#### **Typical Performance Curves**

1030 - 1090 MHz, 1 ms Pulse, 10% Duty,  $V_{DD}$  = 50 V, Idq = 100 mA,  $T_A$  = 25°C

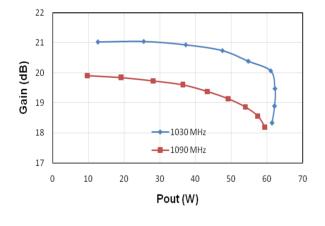
#### Output Power vs. Input Power



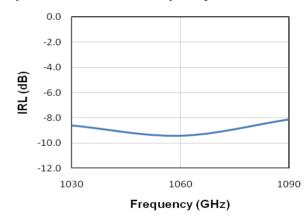
#### Drain Efficiency Vs. Output Power



#### Gain vs. Output Power



#### Input Return Loss vs. Frequency





GaN on SiC HEMT Pulsed Power Transistor 45 W Peak, DC-3500 MHz, 1 ms Pulse, 10% Duty

Rev. V2

#### Outline Drawing MAGX-000035-045000

